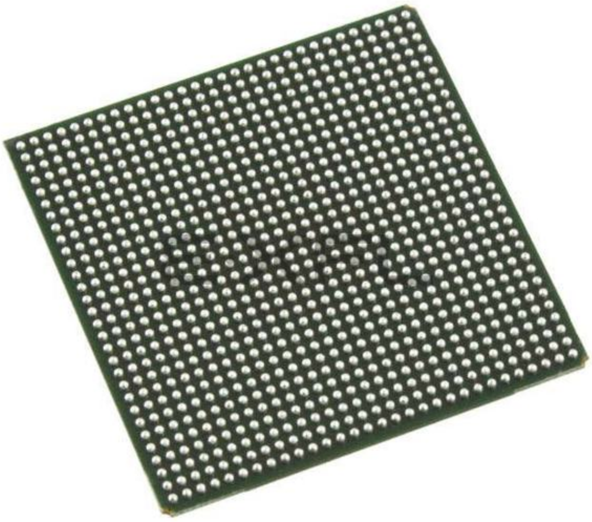


Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	3750
Number of Logic Elements/Cells	15000
Total RAM Bits	1054720
Number of I/O	300
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	900-BBGA
Supplier Device Package	900-FPBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfsc3ga15e-6f900c

DLLs and dynamic glitch free clock MUXs which are required in today's high end system designs. High-speed, high-bandwidth I/O make this family ideal for high-throughput systems.

The ispLEVER® design tool from Lattice allows large complex designs to be efficiently implemented using the LatticeSC family of FPGA devices. Synthesis library support for LatticeSC is available for popular logic synthesis tools. The ispLEVER tool uses the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the LatticeSC device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Lattice provides many pre-designed IP (Intellectual Property) ispLeverCORE™ modules for the LatticeSC family. By using these IPs as standardized blocks, designers are free to concentrate on the unique aspects of their design, increasing their productivity.

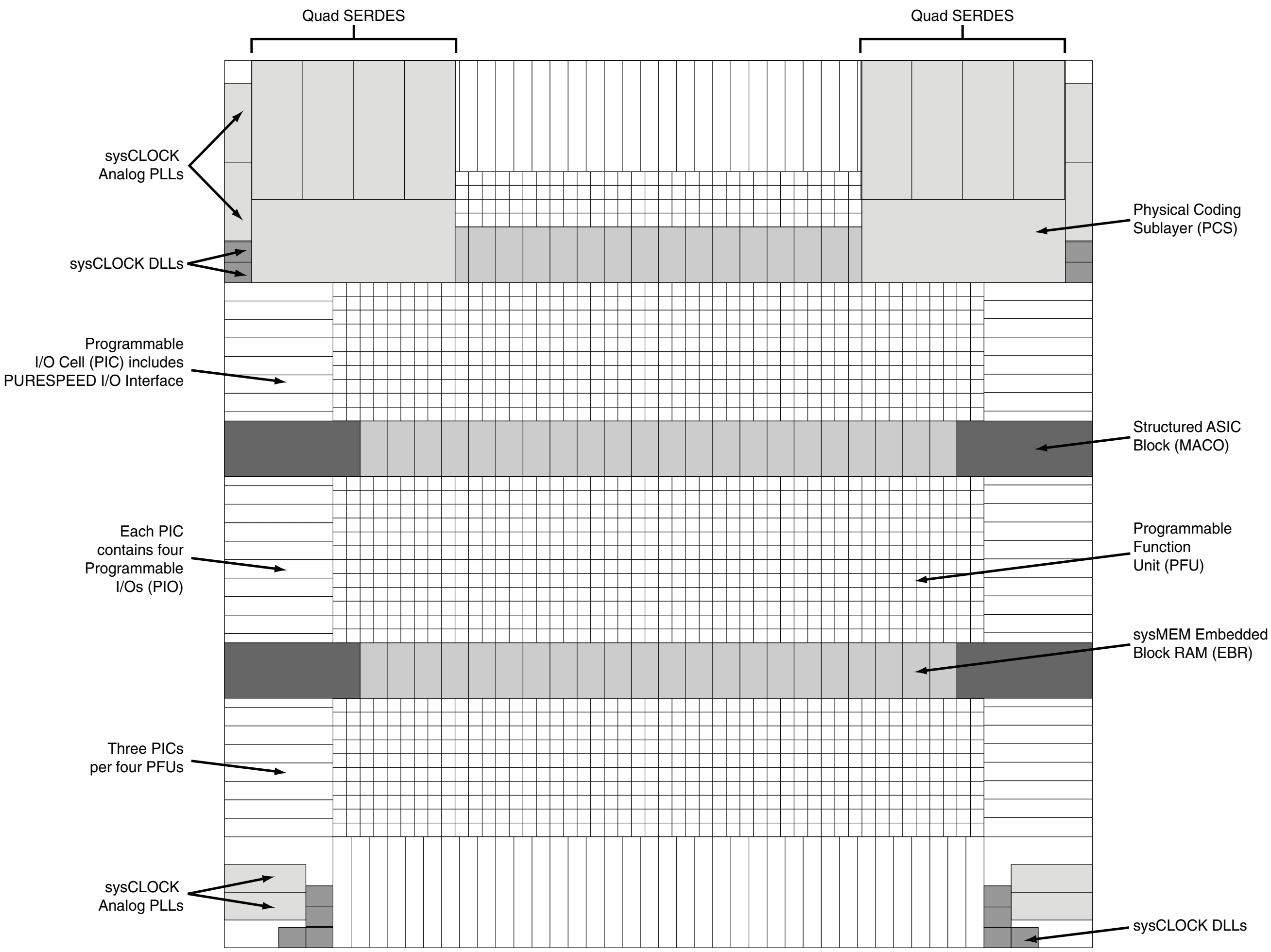
Innovative high-performance FPGA architecture, high-speed SERDES with PCS support, sysMEM embedded memory and high performance I/O are combined in the LatticeSC to provide excellent performance for today's leading edge systems designs. Table 1-3 details the performance of several common functions implemented within the LatticeSC.

Table1-3. Speed Performance for Typical Functions[1]

Functions	Performance (MHz)[2]
32-bit Address Decoder	539
64-bit Address Decoder	517
32:1 Multiplexer	779
64-bit Adder (ripple)	353
32x8 Distributed Single Port (SP) RAM	768
64-bit Counter (up or down counter, non-loadable)	369
True Dual-Port 1024x18 bits	372
FIFO Port A: x36 bits, B: x9 bits	375

1. For additional information, see Typical Building BLock Function Performance table in this data sheet.
2. Advance information (-7 speed grade).

Figure 2-1. Simplified Block Diagram (Top Level)



PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR 16x2 x 4 DPR 16x2 x 2	ROM 16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR 16x4 x 2 DPR 16x4 x 1	ROM 16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR 16x8 x 1	ROM 16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM 16x8 x1

Routing

There are many resources provided in the LatticeSC devices to route signals individually or as busses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

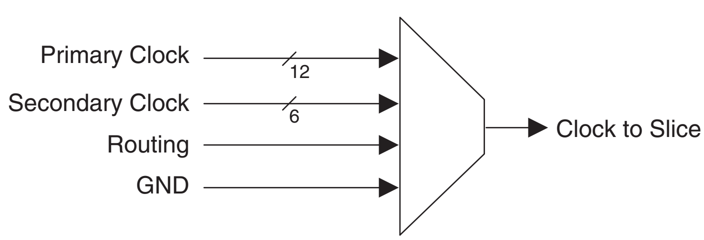
The inter-PFU connections are made with x1 (spans two PFU), x2 (spans three PFU) and x6 (spans seven PFU) resources. The x1 and x2 connections provide fast and efficient connections in horizontal, vertical and diagonal directions. All connections are buffered to ensure high-speed operation even with long high-fanout connections.

The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

sysCLOCK Network

The LatticeSC devices have three distinct clock networks for use in distributing high-performance clocks within the device: primary clocks, secondary clocks and edge clocks. In addition to these dedicated clock networks, users are free to route clocks within the device using the general purpose routing. Figure 2-4 shows the clock resources available to each slice.

Figure 2-4. Slice Clock Selection



Note: GND is available to switch off the network.

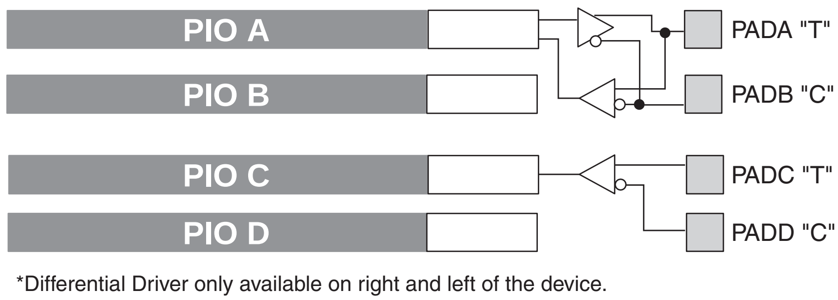
Primary Clock Sources

LatticeSC devices have a wide variety of primary clock sources available. Primary clocks sources consists of the following:

- Primary clock input pins
- Edge clock input pins
- Two outputs per DLL

high-speed interfaces in the LatticeSC devices. Figure 2-18 shows how differential receivers and drivers are arranged between PIOs.

Figure 2-18. Differential Drivers and Receivers



PIO

The PIO contains five blocks: an input register block, output register block, tristate register block, update block, and a control logic block. These blocks contain registers for both single data rate (SDR), double data rate (DDR), and shift register operation along with the necessary clock and selection logic.

Input Register Block

The input register block contains delay elements and registers that can be used to condition signals before they are passed to the device core. Figure 2-20 show the diagram of the input register block. The signal from the PURE-SPEED I/O buffer (DI) enters the input register block and can be used for three purposes, as a source for the combinatorial (INDD) and clock outputs (INCK), the input into the SDR register/latch block and the input to the delay block. The output of the delay block can be used as combinatorial (INDD) and clock (INCK) outputs, an input to the DDR/Shift Register Block or an input into the SDR register block.

Input SDR Register/Latch Block

The SDR register/latch block has a latch and a register/latch that can be used in a variety of combinations to provide a registered or latched output (INFF). The latch operates off high-speed input clocks and latches data on the positive going edge. The register/latch operates off the low-speed input clock and registers/latches data on the positive going edge. Both the latch and the register/latch have a clock enable input that is driven by the input clock enable. In addition both have a variety of programmable options for set/reset including, set or reset, asynchronous or synchronous Local Set Reset LSR (LSR has precedence over CE) and Global Set Reset GSR enable or disable. The register and latch LSR inputs are driven from LSRI, which is generated from the PIO control MUX. The GSR inputs are driven from the GSR output of the PIO control MUX, which allows the global set-reset to be disabled on a PIO basis.

Input Delay Block

The delay block uses 144 tapped delay lines to obtain coarse and fine delay resolution. These delays can be adjusted during configuration or automatically via DLL or AIL blocks. The Adaptive Input Logic (AIL) uses this delay block to adjust automatically the delay in the data path to ensure that it has sufficient setup and hold time.

The delay line in this block matches the delay line that is used in the 12 on-chip DLLs. The delay line can be set via configuration bits or driven from a calibration bus that allows the setting to be controlled either from one of the on-chip DLLs or user logic. Controlling the delay from one of the on-chip DLLs allow the delay to be calibrated to the DLL clock and hence compensated for the variations in process, voltage and temperature.

VDDAX25 needs to be connected independent of the use of the SERDES. This supply is used to control the SERDES CML I/O regardless of the SERDES being used in the design.

Supported Source Synchronous Interfaces

The LatticeSC devices contain a variety of hardware, such as delay elements, DDR registers and PLLs, to simplify the implementation of Source Synchronous interfaces. Table 2-11 lists Source Synchronous and DDR/QDR standards supported in the LatticeSC. For additional detail refer to technical information at the end of the data sheet.

Table 2-11. Source Synchronous Standards Table[1]

Source Synchronous Standard	Clocking	Speeds (MHz)	Data Rate (Mbps)
RapidIO	DDR	500	1000
SPI4.2 (POS-PHY4)/NPSI	DDR	500	1000
SFI4/XSBI	DDR SDR	334 667	667
XGMII	DDR	156.25	312
CSIX	SDR	250	250
QDRII/QDRII+ memory interface	DDR	300	600
DDR memory interface	DDR	240	480
DDRII memory interface	DDR	333	667
RLDRAM memory interface	DDR	400	800

1. Memory width is dependent on the system design and limited by the number of I/Os in the device.

flexiPCS™ (Physical Coding Sublayer Block)

flexiPCS Functionality

The LatticeSC family combines a high-performance FPGA fabric, high-performance I/Os and large embedded RAM in a single industry leading architecture. LatticeSC devices also feature up to 32 channels of embedded SERDES with associated Physical Coding Sublayer (PCS) logic. The flexiPCS logic can be configured to support numerous industry standard high-speed data transfer protocols.

Each channel of flexiPCS logic contains dedicated transmit and receive SERDES for high-speed, full-duplex serial data transfers at data rates up to 3.8 Gbps. The PCS logic in each channel can be configured to support an array of popular data protocols including SONET (STS-12/STS-12c, STS-48/STS-48c, and TFI-5 support of 10 Gbps or above), Gigabit Ethernet (compliant to the IEEE 1000BASE-X specification), 1.02 or 2.04 Gbps Fibre Channel, PCI-Express, and Serial RapidIO. In addition, the protocol based logic can be fully or partially bypassed in a number of configurations to allow users flexibility in designing their own high-speed data interface.

Protocols requiring data rates above 3.8 Gbps can be accommodated by dedicating either one pair or all four channels in one flexiPCS quad block to one data link. One quad can support full-duplex serial data transfers at data rates up to 15.2 Gbps. A single flexiPCS quad can be configured to support 10Gb Ethernet (with a fully compliant XAUI interface), 10Gb Fibre Channel, and x4 PCI-Express and 4x RapidIO.

The flexiPCS also provides bypass modes that allow a direct 8-bit or 10-bit interface from the SERDES to the FPGA logic which can also be geared to run at 1/2 speed for a 16-bit or 20-bit interface to the FPGA logic. Each SERDES pin can be DC coupled independently and can allow for both high-speed and low-speed operation down to DC rates on the same SERDES pin, as required by some Serial Digital Video applications.

The ispLEVER design tools from Lattice support all modes of the flexiPCS. Most modes are dedicated to applications associated with a specific industry standard data protocol. Other more general purpose modes allow a user to define their own operation. With ispLEVER, the user can define the mode for each quad in a design. Nine modes are currently supported by the ispLEVER design flow:

PURESPEED I/O Differential Electrical Characteristics

LVDS

Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input voltage		0	—	2.4	V
V_{THD}	Differential input threshold ($Q-\overline{Q}$)		+/-100	—	—	mV
V_{CM}	Input common mode voltage		0.05	1.2	2.35	V
I_{IN}	Input current	Power on or power off	—	—	+/-10	µA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	R_T = 100 Ohm	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	R_T = 100 Ohm	0.9V	1.03	—	V
V_{OD}	Output voltage differential	(V_{OP} - V_{OM}), R_T = 100 Ohm	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	(V_{OP} - V_{OM})/2, R_T = 100 Ohm	1.125	1.20	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{SAB}	Output short circuit current	V_{OD} = 0V Driver outputs shorted	—	—	12	mA
T_R, T_F	Output rise and fall times, 20% to 80%	—	—	500	ps	T_R, T_F

Notes:
1. Data is for 3.5mA differential current drive. Other differential driver current options are available.
2. If the low power mode of the input buffer is used, the minimum V_{CM} is 600 mV.

Mini-LVDS

Over Recommended Operating Conditions

Parameter Symbol	Description	Min.	Typ.	Max.	Units
Z_O	Single-ended PCB trace impedance	30	50	75	ohms
R_T	Differential termination resistance	60	100	150	ohms
V_{OD}	Output voltage, differential, $\|V_{OP} - V_{OM}\|$	300	—	600	mV
V_{OS}	Output voltage, common mode, $\|V_{OP} + V_{OM}\|/2$	1	1.2	1.4	V
ΔV_{OD}	Change in V_{OD}, between H and L	—	—	50	mV
ΔV_{ID}	Change in V_{OS}, between H and L	—	—	50	mV
V_{THD}	Input voltage, differential, $\|V_{INP} - V_{INM}\|$	200	—	600	mV
V_{CM}	Input voltage, common mode, $\|V_{INP} + V_{INM}\|/2$	0.3+(V_{THD}/2)	—	2.1-(V_{THD}/2)	
T_R, T_F	Output rise and fall times, 20% to 80%	—	—	500	ps
T_{ODUTY}	Output clock duty cycle	45	—	55	%
T_{IDUTY}	Input clock duty cycle	40	—	60	%

Note: Data is for 6mA differential current drive. Other differential driver current options are available.

Signal Descriptions (Cont.)

Signal Name	I/O	Description
RESP_[ULC/URC]	—	Calibration resistor to be placed between this pin and either ground or RESPN_[ULC/URC]. RESPN_[ULC/URC] is available on select packages. If available, connection of calibration resistor between RESP_[ULC/URC] and RESPN_[ULC/URC] takes precedence over connection of calibration resistor between RESP_[ULC/URC] and ground. Note: only one per side of the device. Value: 4.02K ohm +/- 1% ohm.
RESPN_[ULC/URC]	—	Available on selected packages. If available, calibration resistor should be placed between RESP_[ULC/URC] and RESPN_[ULC/URC] instead of between RESP_[ULC/URC] and ground. Note: only one per side of the device. Value: 4.02K ohm +/- 1% ohm.
[A:D]_VDDIBx_[L/R]	—	Input buffer power supply for channel x (1.2V/1.5V) on left [L] or right [R] side of device.
[A:D]_VDDOBx_[L/R]	—	Output buffer power supply for channel x (1.2V/1.5V) on left [L] or right [R] side of device.
[A:D]_VDDAX25_[L/R]	—	Auxiliary power for input and output termination (2.5V) on left [L] or right [R] side of device.

1. The ispLEVER software tools may specify VDDRX, VDDTX, VDDP and VCCL pins. These pins should be considered VCC12 pins.

Note: Signals listed as Signal A / Signal B define the same physical pin that is used for different functions based on configuration mode.

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
B29	NC	-		NC	-	

1. Differential pair grouping within a PIC is A (True) and B (Complement) and C (True) and D (Complement).
2. The LatticeSC/M15 and LatticeSC/M25 in a 900-pin package supports a 16-bit MPI interface.

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
E22	VCC12	-		VCC12	-	
E21	VCC12	-		VCC12	-	
E3	VCC12	-		VCC12	-	
E4	VCC12	-		VCC12	-	
E6	VCC12	-		VCC12	-	
E7	VCC12	-		VCC12	-	
E8	VCC12	-		VCC12	-	
E9	VCC12	-		VCC12	-	
E11	VCC12	-		VCC12	-	
E12	VCC12	-		VCC12	-	
A23	GND	-		GND	-	
A31	GND	-		GND	-	
AA13	GND	-		GND	-	
AA15	GND	-		GND	-	
AA18	GND	-		GND	-	
AA20	GND	-		GND	-	
AA26	GND	-		GND	-	
AA6	GND	-		GND	-	
AB10	GND	-		GND	-	
AB24	GND	-		GND	-	
AC14	GND	-		GND	-	
AC22	GND	-		GND	-	
AC29	GND	-		GND	-	
AC3	GND	-		GND	-	
AD11	GND	-		GND	-	
AD19	GND	-		GND	-	
AD27	GND	-		GND	-	
AD7	GND	-		GND	-	
AF12	GND	-		GND	-	
AF18	GND	-		GND	-	
AF24	GND	-		GND	-	
AF30	GND	-		GND	-	
AF4	GND	-		GND	-	
AG15	GND	-		GND	-	
AG21	GND	-		GND	-	
AG9	GND	-		GND	-	
AJ10	GND	-		GND	-	
AJ16	GND	-		GND	-	
AJ20	GND	-		GND	-	
AJ26	GND	-		GND	-	
AJ29	GND	-		GND	-	
AJ4	GND	-		GND	-	
AK13	GND	-		GND	-	
AK17	GND	-		GND	-	
AK23	GND	-		GND	-	
AK7	GND	-		GND	-	
AL1	GND	-		GND	-	
AL32	GND	-		GND	-	
AM2	GND	-		GND	-	
AM31	GND	-		GND	-	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

	LFSC/M40			LFSC/M80		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
L1	PR31A	2		PR43A	2	
T10	PR30D	2		PR42D	2	
U10	PR30C	2		PR42C	2	
N2	PR30B	2		PR42B	2	
M2	PR30A	2		PR42A	2	
R11	PR29D	2		PR37D	2	
P11	PR29C	2		PR37C	2	
N4	PR29B	2		PR37B	2	
M4	PR29A	2		PR37A	2	
N5	PR27D	2		PR35D	2	
M5	PR27C	2		PR35C	2	
L2	PR27B	2		PR35B	2	
K2	PR27A	2		PR35A	2	
P8	PR26D	2		PR33D	2	
N8	PR26C	2		PR33C	2	
J2	PR26B	2		PR33B	2	
H2	PR26A	2		PR33A	2	
M6	PR25D	2		PR31D	2	
L6	PR25C	2		PR31C	2	
K3	PR25B	2		PR31B	2	
J3	PR25A	2		PR31A	2	
M8	PR23D	2	DIFFR_2	PR29D	2	DIFFR_2
L8	PR23C	2	VREF1_2	PR29C	2	VREF1_2
K4	PR23B	2		PR29B	2	
J4	PR23A	2		PR29A	2	
M7	PR22D	2		PR21D	2	
L7	PR22C	2		PR21C	2	
J5	PR22B	2		PR21B	2	
H5	PR22A	2		PR21A	2	
N9	PR21D	2		PR20D	2	
P9	PR21C	2		PR20C	2	
G3	PR21B	2		PR20B	2	
F3	PR21A	2		PR20A	2	
J6	PR18D	2	VREF2_2	PR18D	2	VREF2_2
H6	PR18C	2		PR18C	2	
E2	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C
D2	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C
P10	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A
N10	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A
G4	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D
F4	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
J7	PR16D	2		PR16D	2	
H7	PR16C	2		PR16C	2	
G5	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B	PR16B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
F5	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B	PR16A	2	URC_PLLT_IN_A/URC_PLLT_FB_B

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
F15	PT55A	1	D5/MPI_DATA5	PT74A	1	D5/MPI_DATA5
K14	PT54D	1	D4/MPI_DATA4	PT73D	1	D4/MPI_DATA4
K13	PT54C	1	D3/MPI_DATA3	PT73C	1	D3/MPI_DATA3
B15	PT53B	1	D2/MPI_DATA2	PT73B	1	D2/MPI_DATA2
A15	PT53A	1	D1/MPI_DATA1	PT73A	1	D1/MPI_DATA1
J14	PT51D	1	D16/PCLKC1_3/MPI_DATA16	PT71D	1	D16/PCLKC1_3/MPI_DATA16
H14	PT51C	1	D17/PCLKT1_3/MPI_DATA17	PT71C	1	D17/PCLKT1_3/MPI_DATA17
A16	PT51B	1	D0/MPI_DATA0	PT71B	1	D0/MPI_DATA0
B16	PT51A	1	QOUT/CEON	PT71A	1	QOUT/CEON
J13	PT50D	1	VREF2_1	PT70D	1	VREF2_1
H13	PT50C	1	D18/MPI_DATA18	PT70C	1	D18/MPI_DATA18
D15	PT50B	1	DOUT	PT70B	1	DOUT
E15	PT50A	1	MCA_DONE_IN	PT70A	1	MCA_DONE_IN
J16	PT49D	1	D19/PCLKC1_2/MPI_DATA19	PT69D	1	D19/PCLKC1_2/MPI_DATA19
J17	PT49C	1	D20/PCLKT1_2/MPI_DATA20	PT69C	1	D20/PCLKT1_2/MPI_DATA20
D16	PT49B	1	MCA_CLK_P1_OUT	PT69B	1	MCA_CLK_P1_OUT
E16	PT49A	1	MCA_CLK_P1_IN	PT69A	1	MCA_CLK_P1_IN
H15	PT47D	1	D21/PCLKC1_1/MPI_DATA21	PT67D	1	D21/PCLKC1_1/MPI_DATA21
H16	PT47C	1	D22/PCLKT1_1/MPI_DATA22	PT67C	1	D22/PCLKT1_1/MPI_DATA22
C15	PT47B	1	MCA_CLK_P2_OUT	PT67B	1	MCA_CLK_P2_OUT
C16	PT47A	1	MCA_CLK_P2_IN	PT67A	1	MCA_CLK_P2_IN
L17	PT46D	1	MCA_DONE_OUT	PT66D	1	MCA_DONE_OUT
K17	PT46C	1	BUSYN/RCLK/SCK	PT66C	1	BUSYN/RCLK/SCK
E17	PT46B	1	DP0/MPI_PAR0	PT66B	1	DP0/MPI_PAR0
F17	PT46A	1	MPI_TA	PT66A	1	MPI_TA
G17	PT45D	1	D23/MPI_DATA23	PT65D	1	D23/MPI_DATA23
H17	PT45C	1	DP2/MPI_PAR2	PT65C	1	DP2/MPI_PAR2
A17	PT45B	1	PCLKC1_0	PT65B	1	PCLKC1_0
B17	PT45A	1	PCLKT1_0/MPI_CLK	PT65A	1	PCLKT1_0/MPI_CLK
G18	PT43D	1	DP3/PCLKC1_4/MPI_PAR3	PT63D	1	DP3/PCLKC1_4/MPI_PAR3
H18	PT43C	1	D24/PCLKT1_4/MPI_DATA24	PT63C	1	D24/PCLKT1_4/MPI_DATA24
E18	PT43B	1	MPI_RETRY	PT63B	1	MPI_RETRY
F18	PT43A	1	A0/MPI_ADDR14	PT63A	1	A0/MPI_ADDR14
J18	PT42D	1	A1/MPI_ADDR15	PT61D	1	A1/MPI_ADDR15
J19	PT42C	1	A2/MPI_ADDR16	PT61C	1	A2/MPI_ADDR16
C20	PT42B	1	A3/MPI_ADDR17	PT61B	1	A3/MPI_ADDR17
C19	PT42A	1	A4/MPI_ADDR18	PT61A	1	A4/MPI_ADDR18
K18	PT41D	1	D25/PCLKC1_5/MPI_DATA25	PT60D	1	D25/PCLKC1_5/MPI_DATA25
L18	PT41C	1	D26/PCLKT1_5/MPI_DATA26	PT60C	1	D26/PCLKT1_5/MPI_DATA26
D19	PT41B	1	A5/MPI_ADDR19	PT60B	1	A5/MPI_ADDR19
E19	PT41A	1	A6/MPI_ADDR20	PT60A	1	A6/MPI_ADDR20
H19	PT39D	1	D27/MPI_DATA27	PT59D	1	D27/MPI_DATA27
H20	PT39C	1	VREF1_1	PT59C	1	VREF1_1
A18	PT39B	1	A7/MPI_ADDR21	PT59B	1	A7/MPI_ADDR21
B18	PT39A	1	A8/MPI_ADDR22	PT59A	1	A8/MPI_ADDR22

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

	LFSC/M40			LFSC/M80		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
H21	PT38D	1	D28/PCLKC1_6/MPI_DATA28	PT57D	1	D28/PCLKC1_6/MPI_DATA28
J21	PT38C	1	D29/PCLKT1_6/MPI_DATA29	PT57C	1	D29/PCLKT1_6/MPI_DATA29
A19	PT38B	1	A9/MPI_ADDR23	PT57B	1	A9/MPI_ADDR23
B19	PT38A	1	A10/MPI_ADDR24	PT57A	1	A10/MPI_ADDR24
H22	PT37D	1	D30/PCLKC1_7/MPI_DATA30	PT56D	1	D30/PCLKC1_7/MPI_DATA30
J22	PT37C	1	D31/PCLKT1_7/MPI_DATA31	PT56C	1	D31/PCLKT1_7/MPI_DATA31
F20	PT37B	1	A11/MPI_ADDR25	PT56B	1	A11/MPI_ADDR25
G20	PT37A	1	A12/MPI_ADDR26	PT56A	1	A12/MPI_ADDR26
K21	PT35D	1	D11/MPI_DATA11	PT55D	1	D11/MPI_DATA11
K22	PT35C	1	D12/MPI_DATA12	PT55C	1	D12/MPI_DATA12
A20	PT35B	1	A13/MPI_ADDR27	PT55B	1	A13/MPI_ADDR27
B20	PT35A	1	A14/MPI_ADDR28	PT55A	1	A14/MPI_ADDR28
L21	PT33D	1	A16/MPI_ADDR30	PT53D	1	A16/MPI_ADDR30
L20	PT33C	1	D13/MPI_DATA13	PT53C	1	D13/MPI_DATA13
D20	PT33B	1	A15/MPI_ADDR29	PT53B	1	A15/MPI_ADDR29
E20	PT33A	1	A17/MPI_ADDR31	PT53A	1	A17/MPI_ADDR31
L19	PT30D	1	A19/MPI_TSIZ1	PT52D	1	A19/MPI_TSIZ1
K19	PT30C	1	A20/MPI_BDIP	PT52C	1	A20/MPI_BDIP
D21	PT30B	1	A18/MPI_TSIZ0	PT52B	1	A18/MPI_TSIZ0
E21	PT30A	1	MPI_TEA	PT52A	1	MPI_TEA
M20	PT28D	1	D14/MPI_DATA14	PT51D	1	D14/MPI_DATA14
M19	PT28C	1	DP1/MPI_PAR1	PT51C	1	DP1/MPI_PAR1
F21	PT27B	1	A21/MPI_BURST	PT51B	1	A21/MPI_BURST
G21	PT27A	1	D15/MPI_DATA15	PT51A	1	D15/MPI_DATA15
H24	B_REFCLKP_L	-		B_REFCLKP_L	-	
J24	B_REFCLKN_L	-		B_REFCLKN_L	-	
L22	VCC12	-		VCC12	-	
E26	B_VDDIB3_L	-		B_VDDIB3_L	-	
G22	VCC12	-		VCC12	-	
E22	B_HDINP3_L	-	PCS 361 CH 3 IN P	B_HDINP3_L	-	PCS 361 CH 3 IN P
F22	B_HDINN3_L	-	PCS 361 CH 3 IN N	B_HDINN3_L	-	PCS 361 CH 3 IN N
A21	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P
L24	VCC12	-		VCC12	-	
B21	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N
D22	B_VDDOB3_L	-		B_VDDOB3_L	-	
B22	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N
D23	B_VDDOB2_L	-		B_VDDOB2_L	-	
A22	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P
K24	VCC12	-		VCC12	-	
F23	B_HDINN2_L	-	PCS 361 CH 2 IN N	B_HDINN2_L	-	PCS 361 CH 2 IN N
E23	B_HDINP2_L	-	PCS 361 CH 2 IN P	B_HDINP2_L	-	PCS 361 CH 2 IN P
D26	B_VDDIB2_L	-		B_VDDIB2_L	-	
G23	VCC12	-		VCC12	-	
D27	B_VDDIB1_L	-		B_VDDIB1_L	-	
G24	VCC12	-		VCC12	-	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AD5	PR94C	3	
AE2	PR94B	3	
AD2	PR94A	3	
AC5	PR92D	3	
AB5	PR92C	3	
AF1	PR92B	3	
AE1	PR92A	3	
AA11	PR91D	3	
Y11	PR91C	3	
AC4	PR91B	3	
AB4	PR91A	3	
AA8	PR90D	3	DIFFR_3
AA9	PR90C	3	
AC3	PR90B	3	
AB3	PR90A	3	
AA7	PR79D	3	
Y7	PR79C	3	
AA2	PR79B	3	
Y2	PR79A	3	
AA6	PR77D	3	
Y6	PR77C	3	
Y4	PR77B	3	
W4	PR77A	3	
W11	PR74D	3	
V11	PR74C	3	
W2	PR74B	3	
V2	PR74A	3	
W9	PR71D	3	
V9	PR71C	3	
V1	PR71B	3	
U1	PR71A	3	
W10	PR70D	3	
V10	PR70C	3	
U2	PR70B	3	
T2	PR70A	3	
Y8	PR69D	3	
W8	PR69C	3	VREF1_3
W5	PR69B	3	
V5	PR69A	3	
V7	PR66D	3	PCLKC3_2
U7	PR66C	3	PCLKT3_2
T1	PR66B	3	
R1	PR66A	3	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
J17	PT81C	1	D20/PCLKT1_2/MPI_DATA20
D16	PT81B	1	MCA_CLK_P1_OUT
E16	PT81A	1	MCA_CLK_P1_IN
H15	PT78D	1	D21/PCLKC1_1/MPI_DATA21
H16	PT78C	1	D22/PCLKT1_1/MPI_DATA22
C15	PT78B	1	MCA_CLK_P2_OUT
C16	PT78A	1	MCA_CLK_P2_IN
L17	PT75D	1	MCA_DONE_OUT
K17	PT75C	1	BUSYN/RCLK/SCK
E17	PT75B	1	DP0/MPI_PAR0
F17	PT75A	1	MPI_TA
G17	PT73D	1	D23/MPI_DATA23
H17	PT73C	1	DP2/MPI_PAR2
A17	PT73B	1	PCLKC1_0
B17	PT73A	1	PCLKT1_0/MPI_CLK
G18	PT71D	1	DP3/PCLKC1_4/MPI_PAR3
H18	PT71C	1	D24/PCLKT1_4/MPI_DATA24
E18	PT71B	1	MPI_RETRY
F18	PT71A	1	A0/MPI_ADDR14
J18	PT69D	1	A1/MPI_ADDR15
J19	PT69C	1	A2/MPI_ADDR16
C20	PT69B	1	A3/MPI_ADDR17
C19	PT69A	1	A4/MPI_ADDR18
K18	PT66D	1	D25/PCLKC1_5/MPI_DATA25
L18	PT66C	1	D26/PCLKT1_5/MPI_DATA26
D19	PT66B	1	A5/MPI_ADDR19
E19	PT66A	1	A6/MPI_ADDR20
H19	PT63D	1	D27/MPI_DATA27
H20	PT63C	1	VREF1_1
A18	PT63B	1	A7/MPI_ADDR21
B18	PT63A	1	A8/MPI_ADDR22
H21	PT61D	1	D28/PCLKC1_6/MPI_DATA28
J21	PT61C	1	D29/PCLKT1_6/MPI_DATA29
A19	PT61B	1	A9/MPI_ADDR23
B19	PT61A	1	A10/MPI_ADDR24
H22	PT58D	1	D30/PCLKC1_7/MPI_DATA30
J22	PT58C	1	D31/PCLKT1_7/MPI_DATA31
F20	PT58B	1	A11/MPI_ADDR25
G20	PT58A	1	A12/MPI_ADDR26
K21	PT57D	1	D11/MPI_DATA11
K22	PT57C	1	D12/MPI_DATA12
A20	PT57B	1	A13/MPI_ADDR27
B20	PT57A	1	A14/MPI_ADDR28

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

	LFSC/M80			LFSC/M115		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AL23	PB56D	5		PB58D	5	
AW24	PB57A	5		PB61A	5	
AW23	PB57B	5		PB61B	5	
AN23	PB57C	5		PB61C	5	
AP23	PB57D	5		PB61D	5	
AY23	PB59A	5		PB63A	5	
AY24	PB59B	5		PB63B	5	
AU23	PB59C	5		PB63C	5	
AU22	PB59D	5		PB63D	5	
AV23	PB60A	5		PB66A	5	
AV22	PB60B	5		PB66B	5	
AM22	PB60C	5		PB66C	5	
AL22	PB60D	5		PB66D	5	
BA23	PB61A	5		PB69A	5	
BA22	PB61B	5		PB69B	5	
AN22	PB61C	5		PB69C	5	
AP22	PB61D	5		PB69D	5	
BB23	PB63A	5		PB71A	5	
BB22	PB63B	5		PB71B	5	
AT22	PB63C	5		PB71C	5	
AR22	PB63D	5		PB71D	5	
BB21	PB65A	4		PB73A	4	
BB20	PB65B	4		PB73B	4	
AR21	PB65C	4		PB73C	4	
AT21	PB65D	4		PB73D	4	
BA21	PB66A	4		PB75A	4	
BA20	PB66B	4		PB75B	4	
AP21	PB66C	4		PB75C	4	
AN21	PB66D	4		PB75D	4	
AV21	PB67A	4		PB78A	4	
AV20	PB67B	4		PB78B	4	
AM21	PB67C	4		PB78C	4	
AL21	PB67D	4		PB78D	4	
AY20	PB69A	4		PB81A	4	
AY19	PB69B	4		PB81B	4	
AU21	PB69C	4		PB81C	4	
AU20	PB69D	4		PB81D	4	
AW20	PB70A	4		PB83A	4	
AW19	PB70B	4		PB83B	4	
AP20	PB70C	4		PB83C	4	
AN20	PB70D	4		PB83D	4	
BB19	PB71A	4		PB86A	4	
BB18	PB71B	4		PB86B	4	
AM20	PB71C	4		PB86C	4	
AL20	PB71D	4		PB86D	4	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

	LFSC/M80			LFSC/M115		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
E37	B_HDINN0_L	-	PCS 361 CH 0 IN N	B_HDINN0_L	-	PCS 361 CH 0 IN N
D37	B_HDINP0_L	-	PCS 361 CH 0 IN P	B_HDINP0_L	-	PCS 361 CH 0 IN P
F34	B_VDDIB0_L	-		B_VDDIB0_L	-	
N29	VCC12	-		VCC12	-	
L30	A_VDDIB3_L	-		A_VDDIB3_L	-	
K31	VCC12	-		VCC12	-	
D38	A_HDINP3_L	-	PCS 360 CH 3 IN P	A_HDINP3_L	-	PCS 360 CH 3 IN P
E38	A_HDINN3_L	-	PCS 360 CH 3 IN N	A_HDINN3_L	-	PCS 360 CH 3 IN N
A37	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P
G37	VCC12	-		VCC12	-	
B37	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N
L33	A_VDDOB3_L	-		A_VDDOB3_L	-	
B38	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N
D41	A_VDDOB2_L	-		A_VDDOB2_L	-	
A38	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P
K34	VCC12	-		VCC12	-	
E39	A_HDINN2_L	-	PCS 360 CH 2 IN N	A_HDINN2_L	-	PCS 360 CH 2 IN N
D39	A_HDINP2_L	-	PCS 360 CH 2 IN P	A_HDINP2_L	-	PCS 360 CH 2 IN P
M32	A_VDDIB2_L	-		A_VDDIB2_L	-	
J32	VCC12	-		VCC12	-	
E41	A_VDDIB1_L	-		A_VDDIB1_L	-	
M33	VCC12	-		VCC12	-	
D40	A_HDINP1_L	-	PCS 360 CH 1 IN P	A_HDINP1_L	-	PCS 360 CH 1 IN P
E40	A_HDINN1_L	-	PCS 360 CH 1 IN N	A_HDINN1_L	-	PCS 360 CH 1 IN N
B39	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P
B41	VCC12	-		VCC12	-	
A39	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N
C41	A_VDDOB1_L	-		A_VDDOB1_L	-	
B40	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N
E42	A_VDDOB0_L	-		A_VDDOB0_L	-	
A40	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P
F42	VCC12	-		VCC12	-	
D42	A_HDINN0_L	-	PCS 360 CH 0 IN N	A_HDINN0_L	-	PCS 360 CH 0 IN N
C42	A_HDINP0_L	-	PCS 360 CH 0 IN P	A_HDINP0_L	-	PCS 360 CH 0 IN P
H39	A_VDDIB0_L	-		A_VDDIB0_L	-	
F41	VCC12	-		VCC12	-	
P16	VDDAX25_R	-		VDDAX25_R	-	
P27	VDDAX25_L	-		VDDAX25_L	-	
K39	NC	-		PL32A	7	
L39	NC	-		PL32B	7	
M38	NC	-		PL35A	7	
K40	NC	-		PL36A	7	
L40	NC	-		PL36B	7	
N37	NC	-		PL39A	7	
P37	NC	-		PL39B	7	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
C3	GND	-		GND	-	
C30	GND	-		GND	-	
C33	GND	-		GND	-	
C35	GND	-		GND	-	
C36	GND	-		GND	-	
C39	GND	-		GND	-	
C4	GND	-		GND	-	
C40	GND	-		GND	-	
C7	GND	-		GND	-	
C8	GND	-		GND	-	
D15	GND	-		GND	-	
D21	GND	-		GND	-	
D25	GND	-		GND	-	
D31	GND	-		GND	-	
F4	GND	-		GND	-	
F40	GND	-		GND	-	
G11	GND	-		GND	-	
G17	GND	-		GND	-	
G26	GND	-		GND	-	
G32	GND	-		GND	-	
H14	GND	-		GND	-	
H20	GND	-		GND	-	
H23	GND	-		GND	-	
H29	GND	-		GND	-	
H35	GND	-		GND	-	
H8	GND	-		GND	-	
J3	GND	-		GND	-	
J39	GND	-		GND	-	
L16	GND	-		GND	-	
L27	GND	-		GND	-	
L36	GND	-		GND	-	
L7	GND	-		GND	-	
M19	GND	-		GND	-	
M24	GND	-		GND	-	
M4	GND	-		GND	-	
M40	GND	-		GND	-	
N12	GND	-		GND	-	
N31	GND	-		GND	-	
P35	GND	-		GND	-	
P8	GND	-		GND	-	
R15	GND	-		GND	-	
R28	GND	-		GND	-	
R3	GND	-		GND	-	
R39	GND	-		GND	-	
T11	GND	-		GND	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

	LFSC/M80			LFSC/M115		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AH22	VTT_5	5		VTT_5	5	
AJ22	VTT_5	5		VTT_5	5	
AJ23	VTT_5	5		VTT_5	5	
AJ24	VTT_5	5		VTT_5	5	
AJ25	VTT_5	5		VTT_5	5	
AB28	VTT_6	6		VTT_6	6	
AB29	VTT_6	6		VTT_6	6	
AE29	VTT_6	6		VTT_6	6	
AJ30	VTT_6	6		VTT_6	6	
AA28	VTT_7	7		VTT_7	7	
AA29	VTT_7	7		VTT_7	7	
R31	VTT_7	7		VTT_7	7	
V29	VTT_7	7		VTT_7	7	
Y24	GND	-		GND	-	
Y26	GND	-		GND	-	
Y8	GND	-		GND	-	
Y35	GND	-		GND	-	
AA16	VCC12	-		VCC12	-	
AA27	VCC12	-		VCC12	-	
AB16	VCC12	-		VCC12	-	
AB27	VCC12	-		VCC12	-	
AF16	VCC12	-		VCC12	-	
AF27	VCC12	-		VCC12	-	
AG17	VCC12	-		VCC12	-	
AG21	VCC12	-		VCC12	-	
G33	NC	-		NC	-	
G10	NC	-		NC	-	
M15	NC	-		NC	-	
L15	NC	-		NC	-	
K16	NC	-		NC	-	
J16	NC	-		NC	-	
M18	NC	-		NC	-	
L18	NC	-		NC	-	
M25	NC	-		NC	-	
L25	NC	-		NC	-	
J27	NC	-		NC	-	
K27	NC	-		NC	-	
L28	NC	-		NC	-	
M28	NC	-		NC	-	

1. Differential pair grouping within a PIC is A (True) and B (Complement) and C (True) and D (Complement).
2. The LatticeSC/M80 and LatticeSC/M115 in a 1704-pin package supports a 32-bit MPI interface.

Lead-Free Packaging

Commercial

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA15E-7FN256C	-7	Lead-Free fpBGA	256	COM	15.2
LFSC3GA15E-6FN256C	-6	Lead-Free fpBGA	256	COM	15.2
LFSC3GA15E-5FN256C	-5	Lead-Free fpBGA	256	COM	15.2
LFSC3GA15E-7FN900C	-7	Lead-Free fpBGA	900	COM	15.2
LFSC3GA15E-6FN900C	-6	Lead-Free fpBGA	900	COM	15.2
LFSC3GA15E-5FN900C	-5	Lead-Free fpBGA	900	COM	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA15EP1-7FN256C	-7	Lead-Free fpBGA	256	COM	15.2
LFSCM3GA15EP1-6FN256C	-6	Lead-Free fpBGA	256	COM	15.2
LFSCM3GA15EP1-5FN256C	-5	Lead-Free fpBGA	256	COM	15.2
LFSCM3GA15EP1-7FN900C	-7	Lead-Free fpBGA	900	COM	15.2
LFSCM3GA15EP1-6FN900C	-6	Lead-Free fpBGA	900	COM	15.2
LFSCM3GA15EP1-5FN900C	-5	Lead-Free fpBGA	900	COM	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA25E-7FN900C	-7	Lead-Free fpBGA	900	COM	25.4
LFSC3GA25E-6FN900C	-6	Lead-Free fpBGA	900	COM	25.4
LFSC3GA25E-5FN900C	-5	Lead-Free fpBGA	900	COM	25.4
LFSC3GA25E-7FFN1020C[1]	-7	Lead-Free Organic fcBGA	1020	COM	25.4
LFSC3GA25E-6FFN1020C[1]	-6	Lead-Free Organic fcBGA	1020	COM	25.4
LFSC3GA25E-5FFN1020C[1]	-5	Lead-Free Organic fcBGA	1020	COM	25.4
LFSC3GA25E-7FFAN1020C	-7	Lead-Free Organic fcBGA Revision 2	1020	COM	25.4
LFSC3GA25E-6FFAN1020C	-6	Lead-Free Organic fcBGA Revision 2	1020	COM	25.4
LFSC3GA25E-5FFAN1020C	-5	Lead-Free Organic fcBGA Revision 2	1020	COM	25.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA25EP1-7FN900C	-7	Lead-Free fpBGA	900	COM	25.4
LFSCM3GA25EP1-6FN900C	-6	Lead-Free fpBGA	900	COM	25.4
LFSCM3GA25EP1-5FN900C	-5	Lead-Free fpBGA	900	COM	25.4
LFSCM3GA25EP1-7FFN1020C[1]	-7	Lead-Free Organic fcBGA	1020	COM	25.4
LFSCM3GA25EP1-6FFN1020C[1]	-6	Lead-Free Organic fcBGA	1020	COM	25.4
LFSCM3GA25EP1-5FFN1020C[1]	-5	Lead-Free Organic fcBGA	1020	COM	25.4
LFSCM3GA25EP1-7FFAN1020C	-7	Lead-Free Organic fcBGA Revision 2	1020	COM	25.4
LFSCM3GA25EP1-6FFAN1020C	-6	Lead-Free Organic fcBGA Revision 2	1020	COM	25.4
LFSCM3GA25EP1-5FFAN1020C	-5	Lead-Free Organic fcBGA Revision 2	1020	COM	25.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.

LatticeSC/M Family Data Sheet Revision History

December 2011 **Data Sheet DS1004**

Date	Version	Section	Change Summary
February 2006	01.0	—	Initial release.
March 2006	01.1	Introduction	SC25 1020 I/O count changed to 476.
		Architecture	Changed ROM 16X4 to ROM 16X2.
			Changed “X2 or X4” to “DIV2 or DIV4”.
			Added Global Set/Reset Section.
		DC and Switching Characteristics	Added notes 5 and 6 to Recommended Operating Conditions table.
			Added Power Supply Ramp Rates table.
			Removed -5 and -6 speed grades from Typical Building Block Performance table.
			Added Input Delay Timing table.
			Added Synchronous GSR Timing table.
		Pinout Information	Expanded PROBE_VCC and PROBE_GND description.
			Removed A-RXREFCLKP_[L/R] from Signal Description table.
			Added RESP_[ULC/URC] to Signal Description table.
			Added notes 1 and 2 to Signal Description table.
			Changed number of NCs to 28.
			Changed number of SERDES (signal + power supply) to 74.
			Removed RESP balls from NC list (B2, C2, B29, C29).
			Added note to VTT table.
			Changed RxRefclk (B2 and C2) to NC.
			Added RESP_ULC.
			Added RESP_URC.
			Changed RxRefclk (B29 and C29) to NC.
June 2006	01.2	Introduction	Changed SERDES min bandwidth from 622 Mbps to 600 Mbps.
			Changed max SERDES bandwidth from 3.4 Gbps to 3.8 Gbps.
			Corrected number of package I/Os for the SC80 and SC115 1704 pin packages.
			Updated speed performance for typical functions with ispLEVER 6.0 values.
		Architecture	Changed “When these pins are not used they should be left unconnected.” with “Unused VTT pins should be connected to GND if the internal or external VCMT function is not used in the bank. If the internal or external VCMT function for differential input termination is used, the VTT pins should be unconnected and allowed to float.”
			Added “SERDES Power Supply Sequencing Requirements” section.
			Changed total bandwidth per quad from 13.6 Gbps to 15.2 Gbps.
			Added the accuracy of the temperature-sensing diode to be typically +/-10 °C. Also referred to a temperature-sensing diode application note for more information.
		DC and Switching Characteristics	Changed “CTAP” to “internal or external VCMT”.
			Changed VCC12 parameter to include VDDP, VDDTX and VDDRX.
			Changed typical values to match ispLEVER 6.0 Power Calculator.